

Electronic Acknowledgement Receipt

EFS ID:	6077090
Application Number:	10553647
International Application Number:	
Confirmation Number:	5573
Title of Invention:	Resin composition for mold used in forming micropattern, and method for fabricating organic mold therefrom
First Named Inventor/Applicant Name:	Tae Wan Kim
Customer Number:	79681
Filer:	Eugene Lieberstein/Audrey de Souza
Filer Authorized By:	Eugene Lieberstein
Attorney Docket Number:	DE1657
Receipt Date:	15-SEP-2009
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Application Type:	U.S. National Stage under 35 USC 371

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Payment Type	Deposit Account
Payment was successfully received in RAM	\$830
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Request for Continued Examination (RCE)	DE1657_RCE.pdf	72617 a3119e6017bd88f37a1095966125bd45a1c 83uD	no	2

Warnings:

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2	Amendment Submitted/Entered with Filing of CPA/RCE	DE1657_AMENDMENT.pdf	247731 09a9ee5fed3661c994d4b4e452ae16f4d0 b3517	no	9
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Warnings:

Information:

3	Information Disclosure Statement (IDS) Filed (SB/08)	DE1657_IDS.pdf	158260 144e9614d450ad8fe4e722de1a1496ce15a0 0a30b	no	4
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4	Foreign Reference	DE1657_ABSTRACTS.pdf	215661 620eb9185be286053e62fe6ba7d095bb87 cc3d5c	no	6
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5	Fee Worksheet (PTO-875)	fee-info.pdf	33498 c093916127e23884142e752bd0f13ec01 45b9d	no	2
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If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

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